## MSKSEMI















**ESD** 

TVS

TSS

MOV

GDT

**PLED** 

# Broduct data sheet



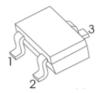
SS8050W













**\$\$8050W** TRANSISTOR (NPN)

**FEATURES** 

Complimentary to SS8550W

**MARKING: Y1** 

1. BASE 2. EMITTER

3. COLLECTOR

**SOT-323** 

#### MAXIMUM RATINGS (T<sub>a</sub>=25℃ unless otherwise noted)

Symbol	Parameter	Value	Unit
V <sub>CBO</sub>	Collector-Base Voltage	40	V
V <sub>CEO</sub>	Collector-Emitter Voltage	25	V
V <sub>EBO</sub>	Emitter-Base Voltage	5	V
lc	Collector Current	1.5	Α
Pc	Collector Power Dissipation	250	mW
R <sub>OJA</sub>	Thermal Resistance From Junction To Ambient	500	°C/W
$T_J, T_stg$	Operation Junction and Storage Temperature Range	-55~+150	℃

#### ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>	I <sub>C</sub> = 100μA, I <sub>E</sub> =0	40			V
Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>	I <sub>C</sub> = 0.1mA, I <sub>B</sub> =0	25			V
Emitter-base breakdown voltage	V <sub>(BR)EBO</sub>	I <sub>E</sub> =100μA, I <sub>C</sub> =0	5			V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> =40V, I <sub>E</sub> =0			0.1	μA
Collector cut-off current	I <sub>CEO</sub>	V <sub>CE</sub> =20V, I <sub>E</sub> =0			0.1	μA
Emitter cut-off current	I <sub>EBO</sub>	$V_{EB}$ = 5V, $I_{C}$ =0			0.1	μA
DC ourrent gain	h <sub>FE(1)</sub>	V <sub>CE</sub> =1V, I <sub>C</sub> = 100mA	120		400	
DC current gain	h <sub>FE(2)</sub>	V <sub>CE</sub> =1V, I <sub>C</sub> = 800mA	40			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> =800mA, I <sub>B</sub> = 80mA			0.5	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	I <sub>C</sub> =800mA, I <sub>B</sub> = 80mA			1.2	V
Transition frequency	f⊤	V <sub>CE</sub> =10V, I <sub>C</sub> = 50mA, f=30MHz	100			MHz
Collector output capacitance	C <sub>ob</sub>	V <sub>CB</sub> =10V,I <sub>E</sub> =0,f=1MHz			15	pF

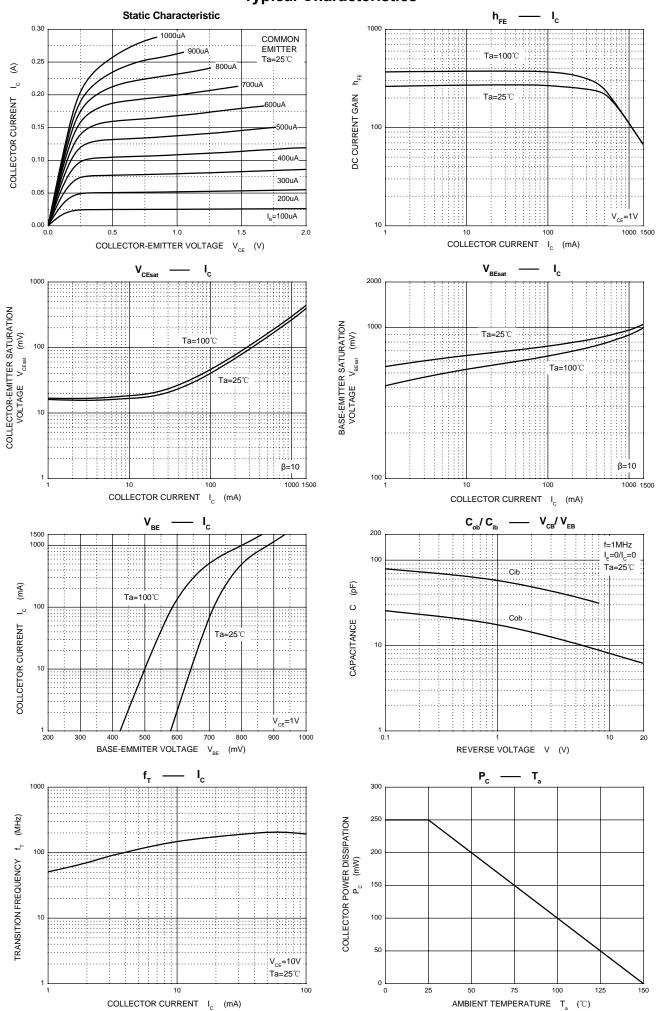
#### **CLASSIFICATION OF hfe(1)**

Rank	L	Н	J
Range	120-200	200-350	300-400

Semiconductor

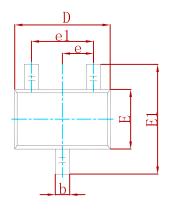


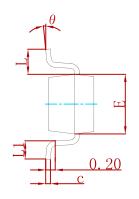
#### **Typical Characteristics**

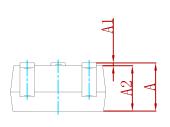




#### **PACKAGE MECHANICAL DATA**

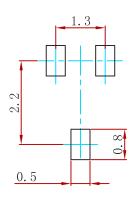






Compleal	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.100	0.035	0.043	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.000	0.035	0.039	
b	0.200	0.400	0.008	0.016	
С	0.080	0.150	0.003	0.006	
D	2.000	2.200	0.079	0.087	
Е	1.150	1.350	0.045	0.053	
E1	2.150	2.450	0.085	0.096	
е	0.65	0 TYP	0.026	3 TYP	
e1	1.200	1.400	0.047	0.055	
L	0.525 REF		0.021 REF		
L1	0.260	0.460	0.010	0.018	
θ	0°	8°	0°	8°	

### Suggested Pad Layout



- 1. Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
SS8050W	SOT-323	3000



Semiconductor

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